

Automatic X-Ray Inspection System for automotive modules and assemblies



The **XT-1300** is an automatic x-ray inspection system, especially designed for the fully automatic inspection of high modules and complete assemblies. The system is equipped with a maintenance-free 130kV microfocus x-ray tube and a flexible carrier system that can be easily adapted to customer specific applications. The integrated test library includes algorithms for standard SMD joint inspection as well as for the inspection of joints on flexible circuit boards.

MIPS_Tune is an off-line programming software package for test program generation with automatic CAD import or alternatively without CAD data. The software supports automatic inspection list generation based on an advanced algorithm library for transmission and off-axis joint inspection.

The integrated rule generation feature allows manual and automatic creation of reliable rules.

The MIPS_Verify module with its closed-loop repair concept is capable for in-line or off-line verification using a graphical board layout display and X-ray image with defect marking. MIPS-Verify can be linked to combined AOI inspection platforms.

The MIPS_SPC Real Time module provides real-time process control with immediate production line feedback.

XT-1300 System Features

- Transmission X-RAY & 3D Slice-Filter Technology
- 130 kV Microfocus X-RAY Tube (sealed)
- Digital Flat Panel Detector (1,5k x 1,5k)
- Efficient Board Handling with conveyor system and programmable XY Table
- Flexible, sample fixture carrier, that can be easily adapted to customer specific applications
- Z-Axis motion for variable field of view size
- Automatic grey-level and geometrical calibration
- Barcode Scanner (1D/2D)
- Single-side load/unload or alternatively pass through setup
- Optional: detector motion system for off-axis images

FEATURES



MatriX Inspection & Process Software

MIPS Hardware

- PC-Station with multi-core processor setup
- Windows 7 Platform

MIPS-Inspection Platform

- Advanced Algorithm Inspection Library for solder joint and component inspection
- Slice-Filter-Technique (SFT) for double-sided boards
- Automatic-Tree Classification (ATC) with Auto-Rule-Generation
- Off-line programming with test-coverage display & auto program generation

Verification & Process Control

- MIPS_Verify link with closed-loop repair
- MIPS_SPC Real Time with real-time SPC

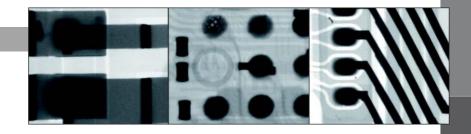




Automatic X-RAY Inspection System for automotive modules and assemblies



Application/Process



Applications

Inspection of big and high modules or assembled devices.

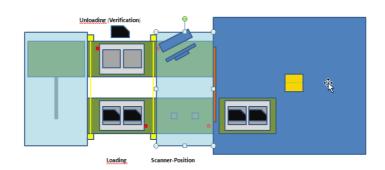
- All standard SMDs and THT/PTH components
- Specific BGA and QFN algorithms
- Advanced PTH/THT algorithms with Filling level check (OA setup)
- Cooling plates/heatsink void inspection

Plus inspection of flexible printed circuit boards:

- Voids
- Soldering defects
- Splash & solder balls

Process Overview (parallel track setup)

- Conveyor system with flexible work-piece holder
- Programmable XY Table
- Loading Station
- Unloading Station with Verification Unit



SPECIFICATION

Di	m	0	ns	:io	ns

Cabinet	.2100 mm(H) x 1850 mm(D) x 1835mm(W	1)
Conveyor system	1050 mm(D) x 1670mm + 750mm(W	()
Weight	approx. 3	t
Conveyor System	Height 900-1000 mr	n
Safe Operation Ter	nperature (Temperature)15 - 32°0	\Box
Line Voltage	400V, 50/60 Hz, 10A avg,, 32 A max	ζ,
	3 phas	е
Air	5-7 bc	ır

Motion System

Programmable X-Y Sample Table	
Driving Distance 500 x	770 mm
Position Repeatability+	/- 25 µm
Z-DriveX-Ro	ay Tube
Z-Axis Driving Distance	220 mm
Z-Movement with cont. magnification for every FOV	change
Optional:	
Angle Shot Capability programmable u, v detec	tor axes

X-Ray Source

Target Voltage	40 -	130kV
Target Current	0 - 3	00 μΑ
Focal Spot Size5 -	10 m	nicron
X-Ray Tube Orientation Fr	d_Wi	ndow

Image Detector

Detector Type	CMOS Detector (1,5k x 1,5k)
Active Inspection Area	115 x 115 mm
Grey Value Resolution	14 bit
Video Output	Camera Link Interface
Video Display	High Resolution 22" TFT

Sample & Conveyor System

Size Workpiece Carrier	640mm x 320mm
Max. Sample Height	240mm
Max. Sample Weight	10 kg

Image Performance

Max. Inspection Area	570mm	x 250mm
FOV & Resolution		
Field-of-View	15 mm	to 35mm

Safety / Regulatory

Full safe, interlocked enclosure. Complies with all U.S. and International standards for cabinet radiography systems. CDRH directives / CE compliant.

Web: www.m-xt.com